TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOSIV)

# **TPCS8213**

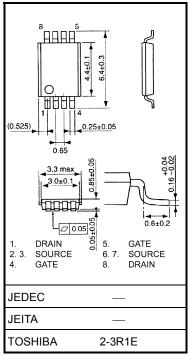
### Lithium Ion Battery Applications

- Small footprint due to a small and thin package
- Low drain-source ON-resistance: R<sub>DS</sub> (ON) = 8.4 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 13 \text{ S (typ.)}$
- Low leakage current: I<sub>DSS</sub> = 10 μA (max) (V<sub>DS</sub> = 20 V)
- Enhancement-mode:  $V_{th} = 0.5 \sim 1.4 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 200 \mu A$ )
- Common drain

## Absolute Maximum Ratings (Ta = 25°C)

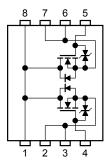
Char	acteristic	Symbol	Rating	Unit	
Drain-source vol	tage	$V_{DSS}$	20	V	
Drain-gate voltag	ge (R <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	20	V	
Gate-source volt	age	V <sub>GSS</sub>	±12	V	
Drain current	DC (Note 1)	I <sub>D</sub>	6	Α	
Diam current	Pulse (Note 1)	I <sub>DP</sub>	24	^	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.1		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.75	W	
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.6	W	
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.35		
Single-pulse avalanche energy (Note 4)		E <sub>AS</sub>	9.4	mJ	
Avalanche currei	nt	I <sub>AR</sub>	6	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E <sub>AR</sub>	0.075	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Unit: mm



Weight: 0.035 g (typ.)

## **Circuit Configuration**



Note: For Notes 1 to 5, see the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

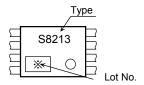
## **MARNING**

[Handling Precaution for Power MOSFET in use of Protection Circuit for Battery Pack]
Flame-retardant resins of UL94-VO flammability class are used in packages, however, they are not noncombustible. Use a unit, for example PTC Thermistor, which can shut off the power supply if a short-circuit occurs. If the power supply is not shut off on the occurring short-circuit, a large short-circuit current will flow continuously, which may cause the device to catch fire or smoke.

## **Thermal Characteristics**

Characteristic	Symbol	Max	Unit		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	114	°C/W	
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	167		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	208		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	357	°C/W	

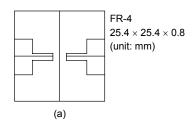
## Marking (Note 6)



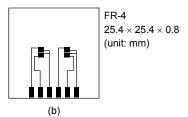
Note 1: Ensure that the channel temperature does not exceed 150°C.

#### Note 2:

a) Device mounted on a glass-epoxy board (a)



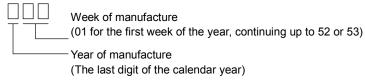
b) Device mounted on a glass-epoxy board (b)



#### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is applied to one device only.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is applied to both devices evenly.)
- Note 4:  $V_{DD}=16~V,~T_{ch}=25^{\circ}C$  (initial),  $L=0.2~mH,~R_{G}=25~\Omega,~I_{AR}=6~A$
- Note 5: Repetitive rating: pulse width limited by max channel temperature
- Note 6: The circle " $\circ$ " on lower right of the marking indicates Pin 1.

\* Weekly code (three digits):



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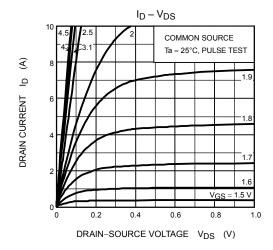
## Electrical Characteristics (Ta = 25°C)

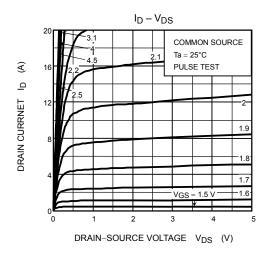
Ch	aracteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff current		I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	10	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	20	_	_	V
		V <sub>(BR)DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	_		
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, I_D = 200 \mu\text{A}$	0.5	_	1.4	٧
			$V_{GS} = 2.5 \text{ V}, I_D = 4.2 \text{ A}$	_	11	18	mΩ
Drain-source ON	-resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4.0 V, I <sub>D</sub> = 4.8 A	_	8.7	13	
			V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4.8 A	_	8.4	12	
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.0 A	6.5	13	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	3140	_	pF
Reverse transfer	Reverse transfer capacitance			_	385	_	
Output capacitance		C <sub>oss</sub>		_	425	_	
	Rise time	t <sub>r</sub>	Act 2 / 4 / 4 / 4 / 4 / 4 / 4 / 4 / 4 / 4 /	_	20	_	
Switching time	Turn-on time	t <sub>on</sub>		_	30		ns
	Fall time	t <sub>f</sub>		_	23		
	Turn-off time	t <sub>off</sub>	V <sub>DD</sub> ≃ 10 V Duty ≦ 1%, t <sub>w</sub> = 10 μs	_	84		
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 16 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6 \text{ A}$		49		
Gate-source charge 1		Q <sub>gs1</sub>			6		nC
Gate-drain ("Mille	Gate-drain ("Miller") charge				13	_	

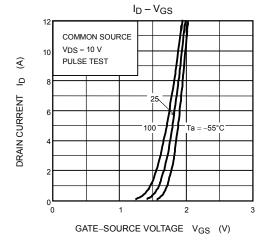
## Source-Drain Ratings and Characteristics (Ta = 25°C)

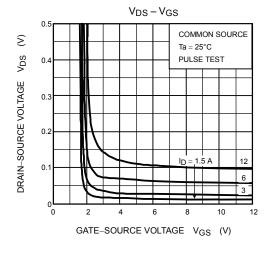
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	24	Α
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = 6 A$ , $V_{GS} = 0 V$		_	-1.2	V

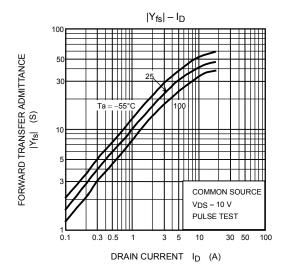
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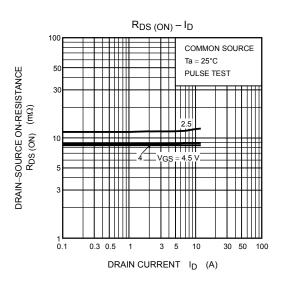


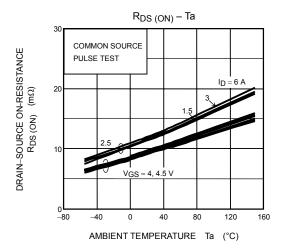


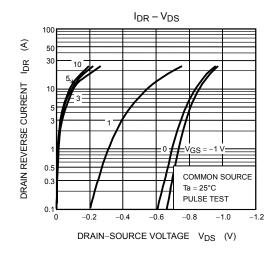


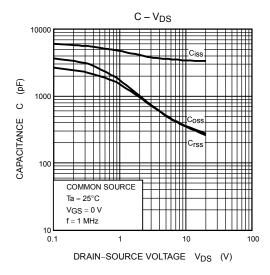


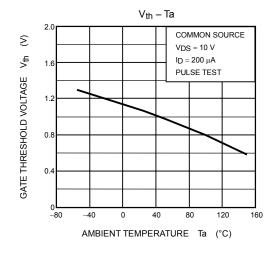


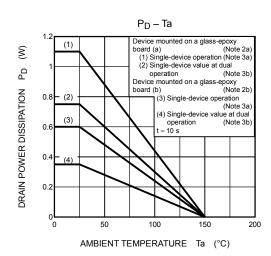


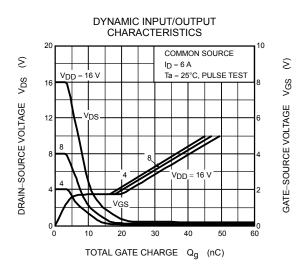




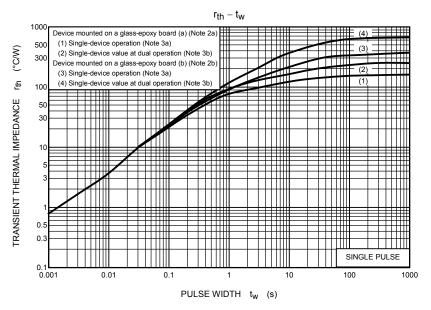




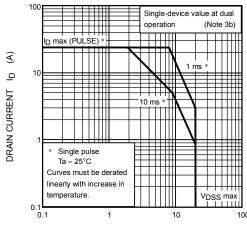




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#### SAFE OPERATING AREA



DRAIN-SOURCE VOLTAGE  $V_{DS}$  (V)

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